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APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.
10/570,665	03/06/2006	Akihiko Endo	P29120	1241
7055 7590 01/07/2009 GREENBLUM & BERNSTEIN, P.L.C. 1950 ROLAND CLARKE PLACE RESTON, VA 20191				
EXAMINER CAMPBELL, SHAUN M				
ART UNIT 2829		PAPER NUMBER		
NOTIFICATION DATE 01/07/2009		DELIVERY MODE ELECTRONIC		

Please find below and/or attached an Office communication concerning this application or proceeding.

The time period for reply, if any, is set in the attached communication.

Notice of the Office communication was sent electronically on above-indicated "Notification Date" to the following e-mail address(es):

gbpatent@gbpatent.com
pto@gbpatent.com

Response to Arguments

1. Applicant's arguments filed 12/10/2008 have been fully considered but they are not persuasive.
2. Applicant argued in substance that "neither Nakazaki nor Masaki discloses or suggests the concept of using different thicknesses of oxide films covering the top and reverse surfaces of a wafer for warping a pre-bonded wafer."
3. Examiner traverses this argument because Nakazaki suggests the concept of using different thicknesses of oxide films covering the top and reverse surfaces of a wafer for warping a pre-bonded wafer. As can be seen in fig 1a-1c and by col. 4, line 67 it is taught that wafers 1a and 1b are warped before bonding, and Nakazaki further teaches that the magnitude of the warp of the wafer depends on the thicknesses of the oxide film (col. 4, line 67 to col. 5, line 9), and further suggests only forming the film on one side of the wafer (fig 2). Therefore even though Nakazaki does not teach that the use of different thicknesses of the film on a top and a bottom surface of the wafer can be used for creating the warping in the wafers, Masaki discloses that it was known at the time the invention was made to use a difference in film thicknesses on a top surface and a bottom surface in order to create a warping (Masaki, abstract). Therefore, someone of ordinary skill in the art at the time the invention was made would have known that along with the different methods of creating warping in a wafer as disclosed

by Nakazaki but that there is also the way of creating warping in a wafer by varying the film thicknesses on the top and the bottom of the wafer as taught by Masaki.

Conclusion

Any inquiry concerning this communication or earlier communications from the examiner should be directed to SHAUN CAMPBELL whose telephone number is (571)270-3830. The examiner can normally be reached on Monday Through Friday 8:00AM-5:30PM EST.

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Nguyen Ha can be reached on (571) 272-1678. The fax phone number for the organization where this application or proceeding is assigned is 571-273-8300.

Information regarding the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Status information for published applications may be obtained from either Private PAIR or Public PAIR. Status information for unpublished applications is available through Private PAIR only. For more information about the PAIR system, see <http://pair-direct.uspto.gov>. Should you have questions on access to the Private PAIR system, contact the Electronic Business Center (EBC) at 866-217-9197 (toll-free). If you would like assistance from a USPTO Customer Service Representative or access to the automated information system, call 800-786-9199 (IN USA OR CANADA) or 571-272-1000.

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